

PS2911-1

R08DS0110EJ0402

Rev.4.02

Dec 6, 2021

HIGH CTR, 4-PIN ULTRA SMALL PACKAGE FLAT-LEAD PHOTOCOUPLER

DESCRIPTION

The PS2911-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications.

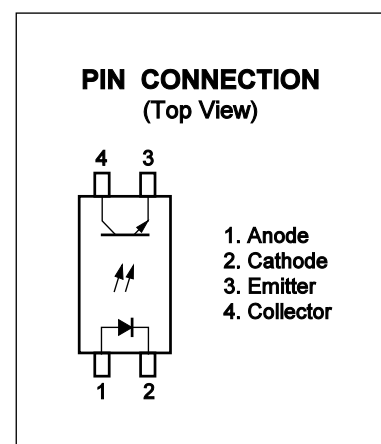
An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30% compared with the PS28xx series.

FEATURES

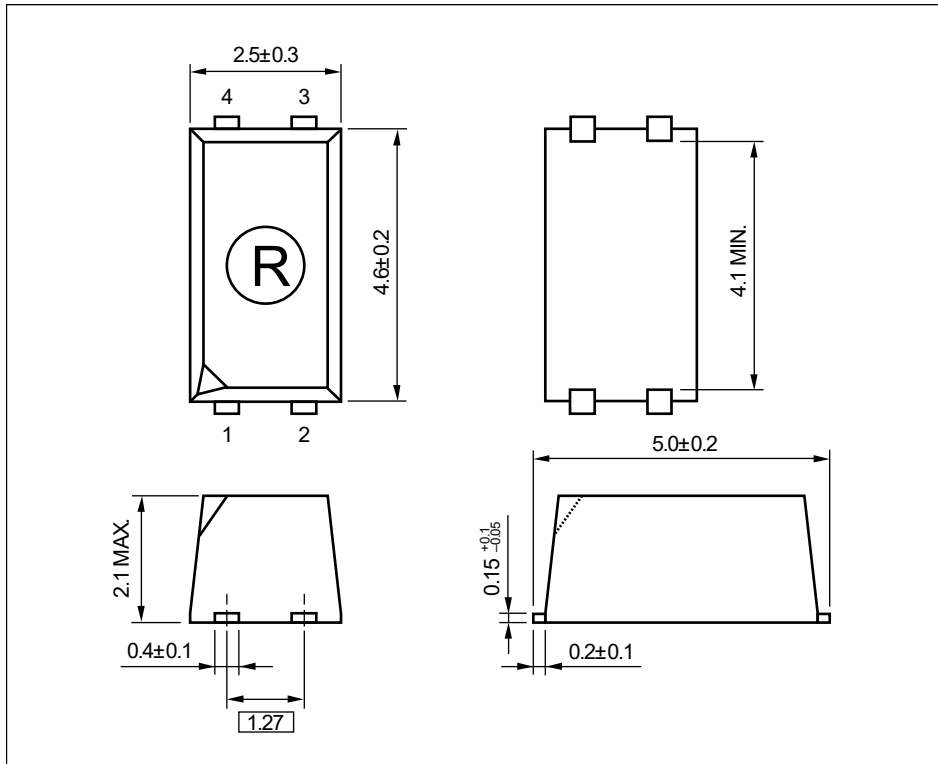
- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- High current transfer ratio (CTR = 200 % TYP. @ $I_F = 1 \text{ mA}$, $V_{CE} = 5 \text{ V}$)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Ordering number of taping product: PS2911-1-F3: 3 500 pcs/reel
- Safety standards
 - UL approved: UL1577, Single protection
 - BSI approved: BS EN 62368-1, Supplementary insulation
 - VDE approved: DIN EN 60747-5-5 (Option)

APPLICATIONS

- DC/DC converter
- Modem/PC card

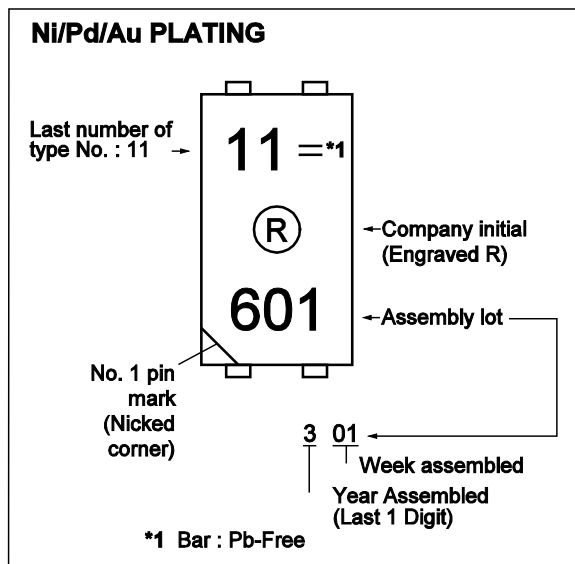


PACKAGE DIMENSIONS (UNIT: mm)



Weight: 0.05g (typ.)

MARKING EXAMPLE



PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

ORDERING INFORMATION

Part Number	Order Number* ¹	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number* ²
PS2911-1	PS2911-1-AX	Pb-Free (Ni/Pd/Au)	50 pcs (Tape 50 pcs cut)	Standard products (UL, BSI approved)	PS2911-1
PS2911-1-F3	PS2911-1-F3-AX		Embossed Tape 3 500 pcs/reel		
PS2911-1-V	PS2911-1-V-AX		50 pcs (Tape 50 pcs cut)	UL, BSI, DIN EN 60747-5-5 approved	
PS2911-1-V-F3	PS2911-1-V-F3-AX		Embossed Tape 3 500 pcs/reel		

Note: *1. When specifying CTR rank, please add "/CTR rank" after Order Number.
ex. L rank : PS2911-1-AX/L

Note: *2. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I_F	50	mA
	Forward Current Derating	$\Delta I_F/^{\circ}\text{C}$	0.5	mA/ $^{\circ}\text{C}$
	Peak Forward Current * ¹	I_{FP}	0.5	A
	Power Dissipation	P_D	60	mW
	Reverse Voltage	V_R	6	V
Detector	Collector to Emitter Voltage	V_{CEO}	40	V
	Emitter to Collector Voltage	V_{ECO}	5	V
	Collector Current	I_C	40	mA
	Power Dissipation Derating	$\Delta P_C/^{\circ}\text{C}$	1.2	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_C	120	mW
Isolation Voltage * ²		BV	2 500	Vr.m.s.
Total Power Dissipation		P_T	160	mW
Operating Ambient Temperature		T_A	-55 to +100	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

Notes: *1. PW = 100 μs , Duty Cycle = 1 %

*2. AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, RH = 60 % between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 1\text{ mA}$	0.9	1.1	1.3	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5	μA
	Terminal Capacitance	C_t	$V = 0\text{ V}, f = 1\text{ MHz}$		15		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$I_F = 0\text{ mA}, V_{CE} = 40\text{ V}$			100	nA
Coupled	Current Transfer Ratio (I_C/I_F) *1	CTR	$I_F = 1\text{ mA}, V_{CE} = 5\text{ V}$	100	200	400	%
	Collector Saturation Voltage	$V_{CE(SAT)}$	$I_F = 1\text{ mA}, I_C = 0.2\text{ mA}$		0.13	0.3	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1\text{ kV}_{DC}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}, f = 1\text{ MHz}$		0.4		pF
	Rise Time *2	t_r	$V_{CC} = 5\text{ V}, I_C = 2\text{ mA}, R_L = 100\text{ }\Omega$		5		μs
	Fall Time *2	t_f			10		
	Turn-on Time *2	t_{on}	$V_{CC} = 5\text{ V}, I_F = 1\text{ mA}, R_L = 5\text{ k}\Omega$		40		μs
	Storage Time *2	t_s			10		
	Turn-off Time *2	t_{off}			120		

Notes: *1. CTR rank

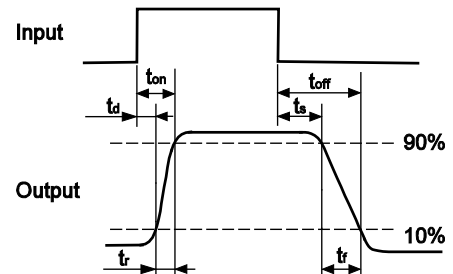
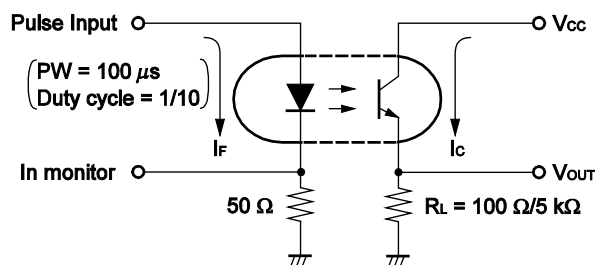
N : 100 to 400 (%)

K : 200 to 400 (%)

L : 150 to 300 (%)

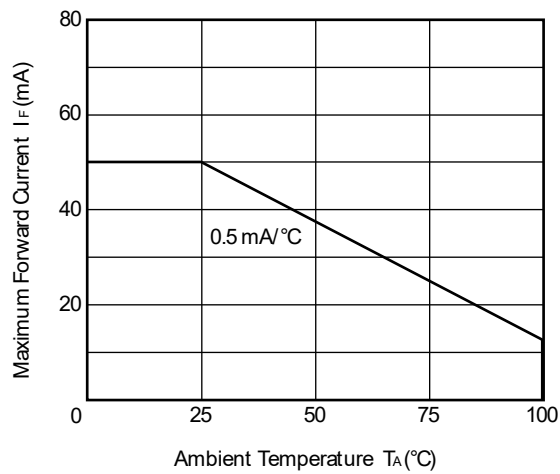
M : 100 to 200 (%)

*2. Test circuit for switching time

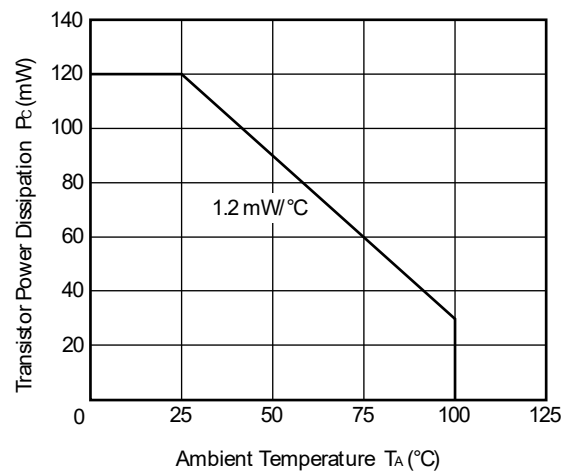


TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

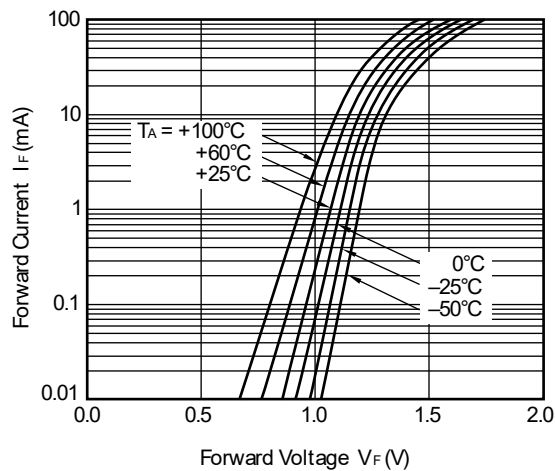
MAXIMUM FORWARD CURRENT vs.
AMBIENT TEMPERATURE



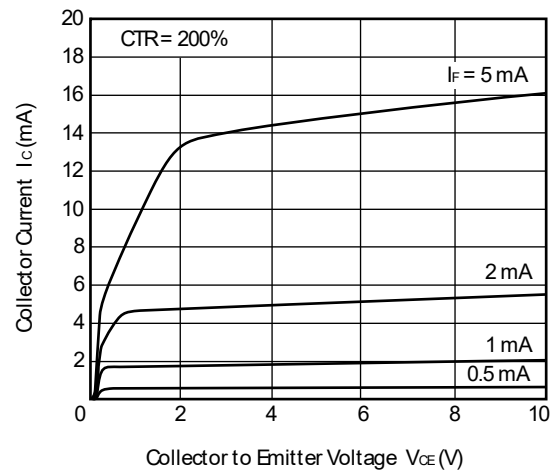
TRANSISTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE



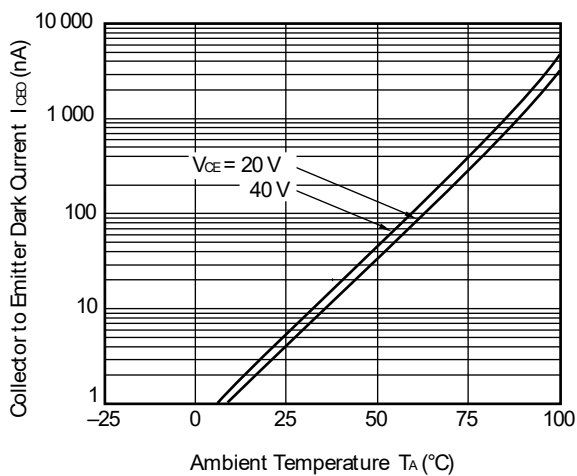
FORWARD CURRENT vs.
FORWARD VOLTAGE



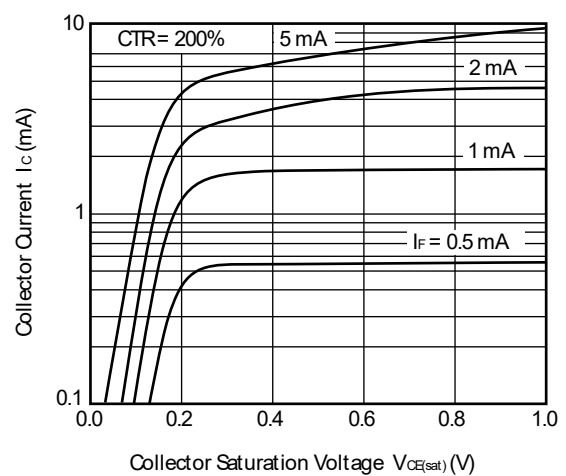
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK
CURRENT vs. AMBIENT TEMPERATURE

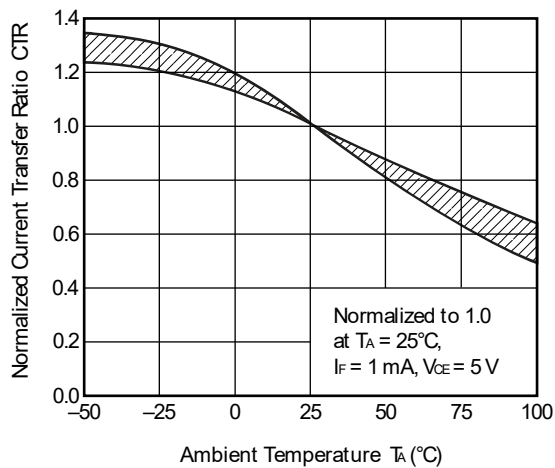


COLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

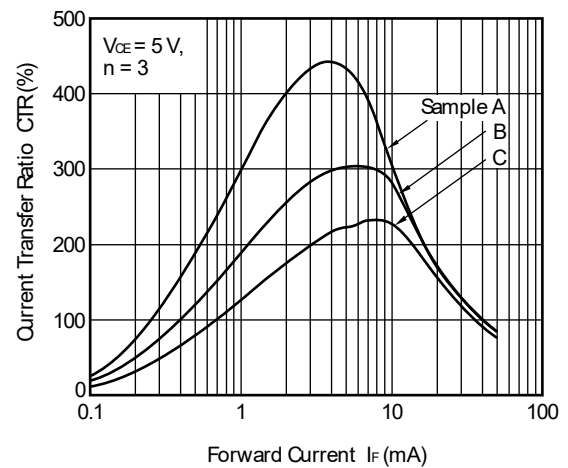


Remark The graphs indicate nominal characteristics.

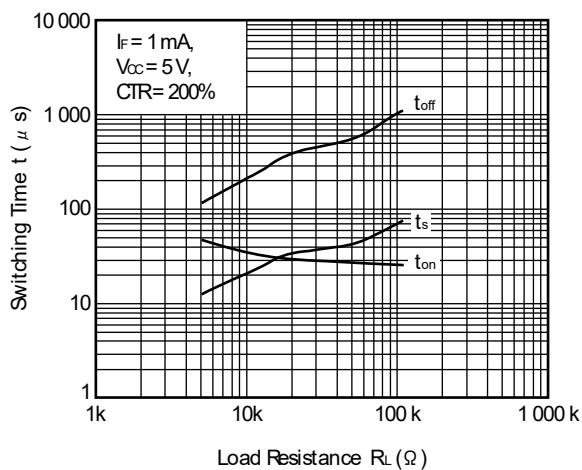
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



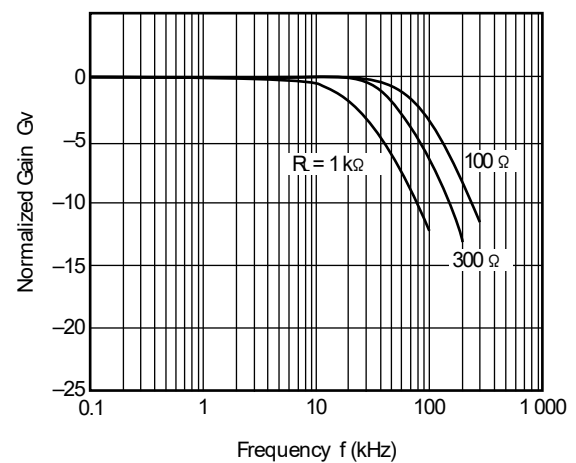
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs. LOAD RESISTANCE



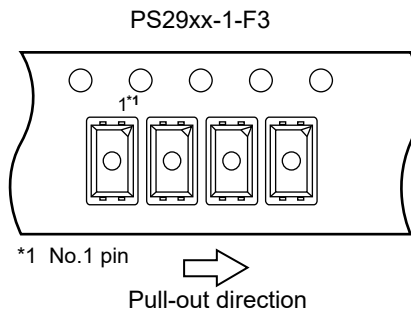
FREQUENCY RESPONSE



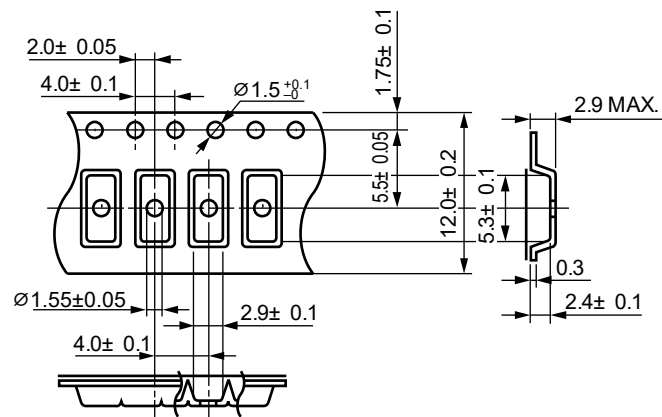
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

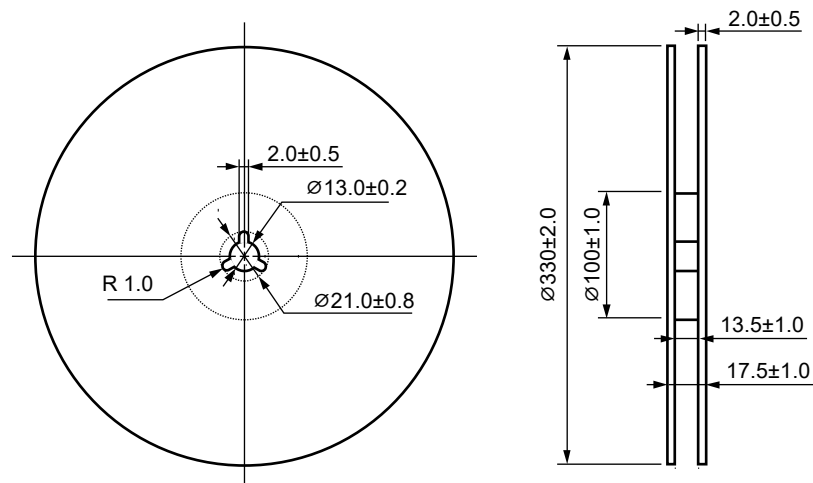
Tape Direction



Outline and Dimensions (Tape)

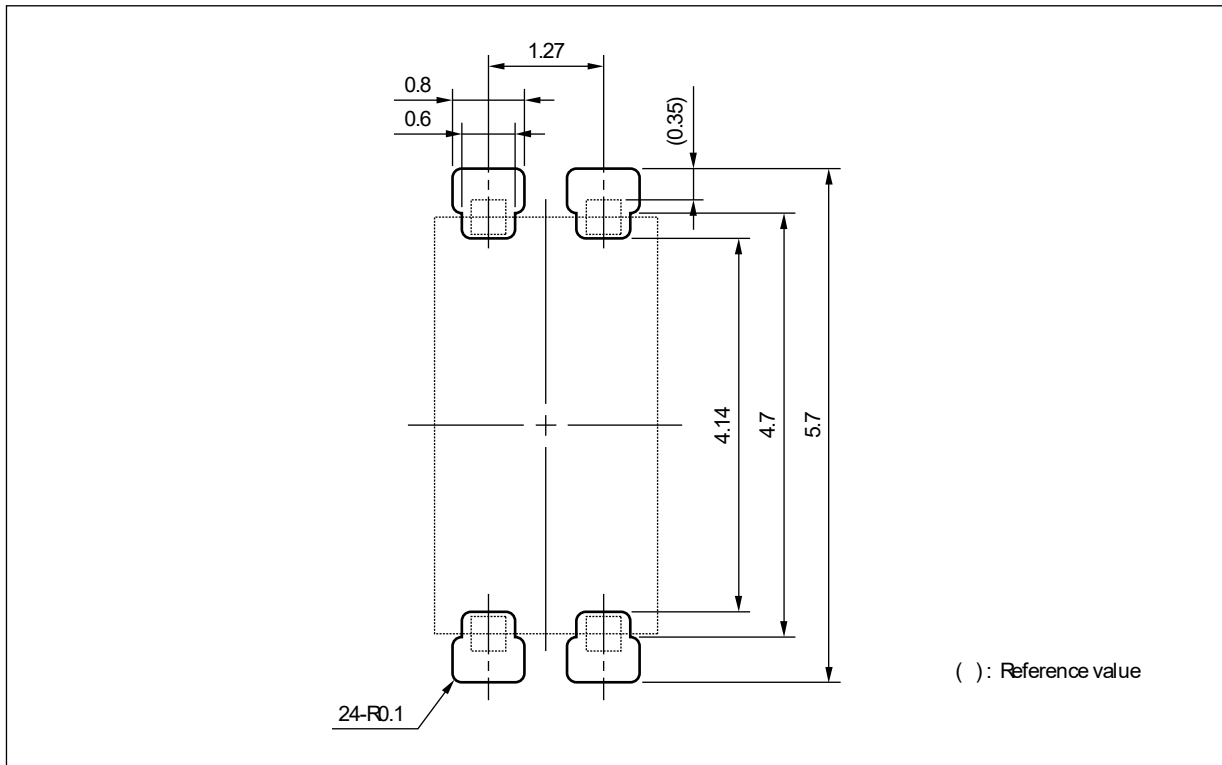


Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.

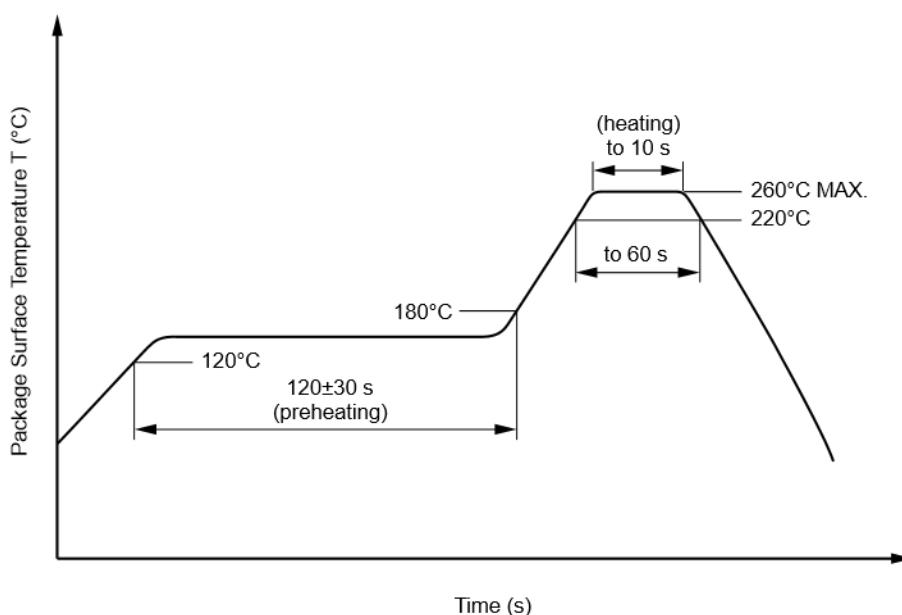
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260 °C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220 °C 60 seconds or less
- Time to preheat temperature from 120 to 180 °C 120 ± 30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120 °C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350 °C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100 °C

(4) Cautions

- Flux Cleaning
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler
Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

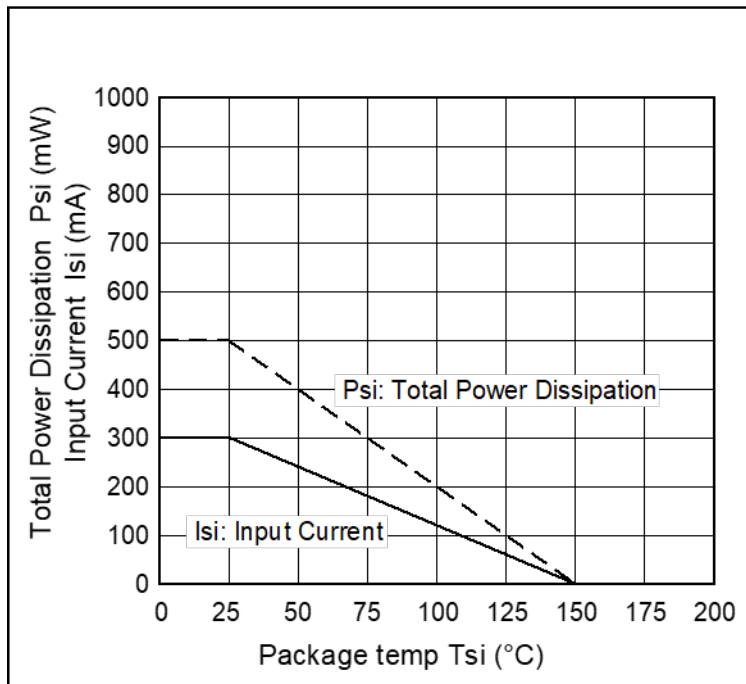
USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

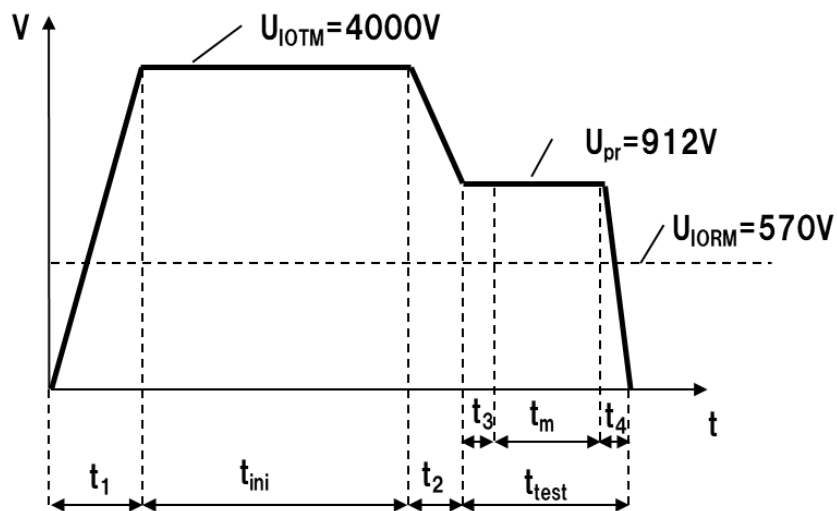
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{IORM} U_{pr}	570 912	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{pr}	1 068	V_{peak}
Highest permissible overvoltage	U_{TR}	4 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25 \text{ °C}$ $V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100 \text{ °C}$	$R_{is \text{ MIN.}}$ $R_{is \text{ MIN.}}$	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $\Psi_i = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	T_{si} I_{si} Ψ_i $R_{is \text{ MIN.}}$	150 300 500 10^9	°C mA mW Ω

Dependence of maximum safety ratings with package temperature



Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

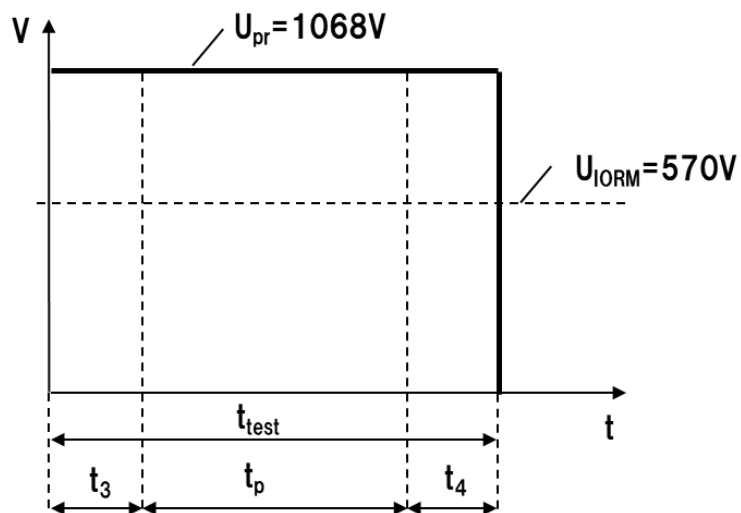
$t_3, t_4 = 1 \text{ sec}$

$t_m \text{ (PARTIAL DISCHARGE)} = 10 \text{ sec}$

$t_{\text{test}} = 12 \text{ sec}$

$t_{\text{ini}} = 60 \text{ sec}$

Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1 \text{ sec}$

$t_p \text{ (PARTIAL DISCHARGE)} = 1.0 \text{ sec}$

$t_{\text{test}} = 1.2 \text{ sec}$

Caution	GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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